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(21)Application number : **05-339160**(71)Applicant : **NIPPON KAYAKU CO LTD**(22)Date of filing : **06.12.1993**(72)Inventor : **YOKOSHIMA MINORU****(54) RADIATION-CURING RESIN COMPOSITION AND CURED PRODUCT THEREFROM****(57)Abstract:**

PURPOSE: To obtain the subject composition which has a high curing rate and can give a cured product excellent in gloss and adhesion to substrate and resistant to cracking even when bent by mixing a specified polymer with a vinyl ether compound and a photo-cationic polymerization initiator.

CONSTITUTION: This resin composition comprises desirably 0.5-40wt.% polymer of an unsaturated compound [e.g. a polymer of (meth)acrylate], desirably 10-99wt.% vinyl ether compound (e.g. tetraethylene glycol divinyl ether) and desirably 0.1-10wt.% photo-cationic polymerization initiator (e.g. triphenylsulfonium hexafluoroantimonate).

LEGAL STATUS

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